

LISTING OF THE CLAIMS

A complete listing of the claims is set forth below.

Claim 1 (currently amended): A non-heat generating jig to be in cold contact with cold contact tails and solder during reflow soldering to effect a solder bond between the contact tails and pads of a board, wherein said jig is provided with diamond-like-carbon coating on at least a portion which is to be in contact with the solder so that the non-adhesive nature of the diamond-like carbon coating is exploited to prevent adhesion between the jig and the solder.

Claim 2 (previously presented): The jig as set forth in claim 1 wherein said jig is provided with the diamond-like-carbon coating on the whole surface which is to be in contact with the solder.

Claim 3 (previously presented): The jig as set forth in claim 1 wherein the diamond-like-carbon coating has a thickness of at least 1 μm .

Claim 4 (currently amended): A method for connecting connection members using a non-heat generating jig which is to be in cold contact with cold contact tails and solder during reflow soldering to effect a solder bond between the contact tails and pads of a board, wherein the jig is provided with diamond-like-carbon coating on at least a portion

which is to be in contact with the solder so that the non-adhesive nature of the diamond-like carbon coating is exploited to prevent adhesion between the jig and the solder.

Claim 5 (original): The method of claim 4 wherein said jig is provided with the diamond-like-carbon coating on the whole surface which is to be in contact with the solder.

Claim 6 (original): The method of claim 4 wherein said diamond-like-carbon coating has a thickness of at least 1 μm .